



Advances in Smart Production & Logistics

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Deadline for manuscript
submissions:

closed (28 February 2023)

Message from the Guest Editors

The list of topics includes but is not limited to:

- Intelligent control and support systems for logistics and supply chain decisions
- Big data analytics for manufacturing and logistics systems and processes
- Smart logistics and intelligence-based optimization and planning methods
- Machine learning applications in manufacturing, logistics, and supply chains
- Digital twin modeling and decision making in the Industry 4.0 era
- Logistics 4.0 and Smart Supply Chain (LSSC)
- Smart application of machine vision
- Smart routing and intelligent logistic transportation systems (ITS))
- Prognostics and health management in smart manufacturing systems
- Artificial intelligence for manufacturing processes
- Fusion of sensor information for manufacturing processes
- Self-optimization models for scheduling for shop floor operations
- Blockchain technology, smart contracts, and traceability in the supply chain
- Autonomy, autonomous vehicles, and drones
- Human-machine collaboration (HMC) and smart human-machine interface





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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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